

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Atty. Docket: 02-GR2-463
Patrick PERILLAT : Applications Branch
Serial No. (Not Yet Assigned) :
Filed: HEREWITH :
For: *SEMICONDUCTOR PACKAGE CONTAINING AN INTEGRATED-CIRCUIT
CHIP SUPPORTED BY ELECTRICAL CONNECTION LEADS*

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SIR:

The attached Form PTO-1449 provides a listing of information which may be relevant to the subject application. This IDS is not intended as a representation that better art is not available, nor that other art than that identified exists; nor that the information provided is prior art; nor that a search has been made.

This IDS is submitted under:

- ☒ 37 CFR 1.97(b) - No Fee.
☐ 37 CFR 1.97(c) - No Fee, with Certification.
☐ 37 CFR 1.97(c) - Fee.
☐ 37 CFR 1.97(d) - Fee, Certification & Petition.

The Commissioner is authorized to charge any required fees under 37 CFR 1.17(p) and (i) (1) to Deposit Account No. **50-1556**.

Respectfully submitted,

Date: 2/18/04

By: 
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Form PTO-1449	U.S. Dept. of Commerce Patent & Trademark Office	Atty. Docket: 02-GR2-463	Serial No. Not Yet Assigned
List of Documents Cited by Applicant (Use several sheets if necessary)		Applicant: Patrick PERILLAT	
		Filing Date: HEREWITH	

U.S. PATENT DOCUMENTS

Ex'rs In'l	Document Number	Date	Name	Class	Sub-class	Filing Date, if applicable
	AA1	5,471,088	November 28, 1995	Song		
	AA2	6,130,115	October 10, 2000	Okumura et al.		
	AA3	6,396,116	May 28, 2002	Kelly et al.		
	AA4	2002/0093026	July 18, 2002	Huang		October 22, 2001
	AA5	2002/0093078	July 18, 2002	Paek		January 14, 2002

FOREIGN PATENT DOCUMENTS

Document Number	Date	Country	Class	Sub-class	Transl'n Yes/No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

AA6	Cha Ki-Bon et al. "Ultra-Thin and Crack-Free Bottom Leaded Plastic (BLP) Package Design", Proceedings of the Electronic Components and Technology Conference, Las Vegas, May 21-24, 1995, New York, IEEE, Vol. Conf. 45, May 21, 1995, pp. 224-228, XP000624973.
AA7	French Preliminary Search Report dated November 18, 2003 for French Application No. 0301964.

Examiner:

Date Considered:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.